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Kulicke & Soffa to Participate at SEMICON Taiwan 2017

Introduces GEN-S Series of High-Performance Ball Bonders

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), announced today that it will be exhibiting at the SEMICON Taiwan trade show in Taipei, September 13 through September 15, 2017.

Kulicke & Soffa will introduce its upcoming GEN-S Series of ball bonding solutions and will also showcase several other leading solutions serving the growing Automotive, Industrial and Advanced Packaging markets.

- 1 **RAPID™ Pro** - the first in the new GEN-S (Smart Generation) Series of high performance ball bonders. RAPID™ Pro introduces advanced process capabilities, real-time monitoring and diagnostics to ensuring the highest quality and efficient assembly serving automotive applications in addition to high-performance, high-reliability semiconductor applications.

"Our latest GEN-S series highlights our continuous focus on research and development to deliver value-added solutions with unparalleled performance to our customers," stated Nelson Wong, Kulicke & Soffa's Vice President of Ball Bonder Business Line & Strategic Solutions Development.

- 1 **Asterion™** - enhanced capability hybrid wedge bonder. It offers an expanded bond area with robust pattern recognition capabilities and extremely tight process controls for advanced interconnect materials.
- 1 **ATPremier™ PLUS** - the versatile wafer level bonder with the smallest footprint that delivers superior wafer-level stud bumping and high productivity with increased efficiency.
- 1 **Hybrid with Horizontal Wafer Feeder** - an innovative solution that enables the combination of ultra-high-speed passive and active placement with high-accuracy flip-chip bonding directly from wafer, ideal for high-volume System-in-Package (SiP), flip-chip, die-attach and wafer-level-package manufacturing. Placement accuracy up to 7µm @ 3 sigma, provides a compelling alternative to existing commercial solutions.

The Company will be demonstrating these products at booth number 540 on level 4 of the Taipei Nangang Exhibition Center.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ:KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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